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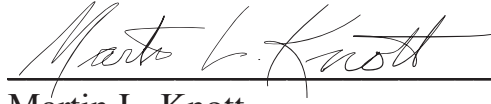
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Martin L. Knott
Metadata and Linked Data Strategist

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**A DESIGN PERSPECTIVE
SECOND EDITION**

**JAN M. RABAEY
ANANTHA CHANDRAKASAN
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*To Kathelijn, Karthiyayani, Krithivasan,
and our Parents*

"Qu'est-ce que l'homme dans la nature?

Un néant a l'égard de l'infini,

un tout al l'égard du néant,

un milieu entre rien et tout."

"What is man in nature?

Nothing in relation to the infinite,

everything in relation to nothing,

a mean between nothing and everything."

Blaise Pascal, *Pensées*, n. 4, 1670.

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